

20th Anniversary of KSDT  
**KISM 2022**

Korean International Semiconductor Conference on Manufacturing Technology 2022

November 13-16, 2022 | Paradise Hotel Busan (Haeundae Beach), Busan, Korea

<b>Session Title:</b>	<b>[MB1] Advanced CMP Process &amp; Scratchless Wet Ceria</b>
<b>Session Date:</b>	<b>November 14 (Mon.), 2022</b>
<b>Session Time:</b>	<b>13:00-14:40</b>
<b>Session Room:</b>	<b>Room B (Grand Ballroom 1, 2F)</b>
<b>Session Chair:</b>	<b>Prof. Jeagun Park (Hanyang Univ., Korea)</b>

**[MB1-1] [Invited] 13:00-13:30**

**Trends of Wet Materials for Cleaning/CMP Process and the Future**

**Hyosan Lee (Samsung Electronics Co., Ltd., Korea)**

**[MB1-2] [Invited] 13:30-14:00**

**Polishing Selectivity Control for Scratch Free Nanoceria Slurry**

**Tomohiro Iwano, Toshiaki Akutsu, Keita Arakawa, Yosuke Hoshi, and Satoyuki Nomura (Showa Denko Materials Co., Ltd., Japan)**

**[MB1-3] 14:00-14:20**

**Ultra Fine Ceria Slurry for Scratch Free CMP with High Selectivity in SiO<sub>2</sub>/Poly-Si/Si<sub>3</sub>N<sub>4</sub>**

**Young Soo Park, Jeong Ho Lee, and Seok Joo Kim (Soulbrain Co., Ltd., Korea)**

**[MB1-4] 14:20-14:40**

**Super Fine Cerium Hydroxide Abrasives for SiO<sub>2</sub>-Film Chemical-Mechanical Planarization Performing Scratch-Free**

**Pil-Su Kim, Young-Hye Son, Gi-Ppeum Jeong, Min-Uk Jeon, Seong-Wan Hong, Hyeong-Ju Jin, Man-Hyup Han, Eun-Seong Kim, Jae-Young Bae, Sung-In Kim, Jin-Hyung Park, and Jea-Gun Park (Hanyang Univ., Korea)**